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DC Whalley, PP Conway, DJ Williams - CAD (Computer Aided Design) Tools for Thermal Management, ..., 1993 - ieeexplore.ieee.org

... of a modelling tool to allow the preproduction **simulation** of ... and printed **circuit** board and ... et al., "Solder joint formation in surface **mount** technology ...

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[\[book\] Printed circuits handbook](#)

CF Coombs Jr - 1987 - McGraw-Hill, Inc. New York, NY, USA

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[Electrical modeling of a BGA package for microwave applications-a layer by layer approach](#)

R Ito, T Hongsmatip, RW Jackson - Electrical Performance of Electronic Packaging, 1998. IEEE ..., 1998 - ieeexplore.ieee.org

... is developed from the characteristics obtained from the **EM simulator**. ... The entire **test circuit** is a through line ... for RF interconnections and to **mount** MMIC chips ...

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[Computer simulation of three-dimensional castellated solder joint geometry in surface mount](#)

[... - group of 6](#) »

G Wang, Z Cheng, C Wang - MODELL SIMUL MATER SCI ENG, 1998 - iop.org

... to be surface mounted to printed **circuit** substrate to ... The **simulation** method can be applied as a ... al 1992 Empirical modeling of surface **mount solder** joints from ...

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[Devices and their Packaging Technology](#)

W Tursky, SE GmbH, G Nuremberg - GaN, 2001 - semikron.com

... signal lines and the need to **mount** fine pitch ... has the ability of replacing all **solder** joints in ... 3D device **simulation** • **circuit simulation** including switching ...

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[A Gunn diode based surface mount 77 GHz oscillator for automotive applications - group of 2](#) »

N Priestley, K Newsome, I Dale, P Norton - Microwave Symposium Digest, 2002 IEEE MTT-S International, 2002 - ieeexplore.ieee.org

... Initially a simple LC **simulation** was used to reproduce Fig ... 4 Schematic **Circuit Diagram** ... gold plated package floor; but alternative die **mounting** technologies are ...

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[MCM-D and direct module attach for RF applications](#)

RG Arnold, CC Faulkner, DJ Pedder - Multichip Modules and High Density Packaging, 1998. ..., 1998 - ieeexplore.ieee.org

... Post layout **simulation** takes account of additional structures ... D modules onto a conventional printed **circuit** board, that ... that employed by flip-chip IC **mounting**. ...

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Sarvar + reflow

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史建卫, 何鹏, 钱乙余, 袁和平 - scholar.lib.cn

... [5] Farhad Sarvar*, Paul P. Conway. A modelling tool for the thermal optimisation of the **reflow** soldering of printed circuit assemblies[J]. Finite Elements in ...[Web Search](#)Combined thermal, thermodynamic and kinetic simulations of the solidification of SnAgCu ...

H Yu, J Kivilahti - Electronic Components and Technology, 2005. ECTC'05. ... - ieeexplore.ieee.org

... thermal modeling and simulation tools have been employed for investigating the solidification of lead-free solder interconnections during **reflow** soldering of ...[Related Articles](#) [Web Search](#) [SL Direct](#)Prediction of Solder Joint Geometry

SM Heinrich - The Mechanics of Solder Alloy Interconnects - ctcnns.nist.gov

... M., Kenmotsu, A., and Ishi, I., "Optimization of Micro-Solder **Reflow** Bonding for the ... Whalley, DC, Conway, PP, Sarvar, F., and Kalantary, M., "The Globule Block ...[Cited by 9](#) [Related Articles](#) [Cached](#) [Web Search](#)SMT 中再流焊工艺建模与仿真 - group of 2 »

毛信龙, 韩国明, 黄丙元, 樊强 - 焊接技术, 2004 - 万方数据资源系统

... [8] Farhad Sarvar, Paul P Conway. A modelling tool for the thermal optimisation of the **reflow** soldering of printed circuit assemblies[J]. FINITE ELEM ANAL DES ...[Related Articles](#) [Web Search](#)再流焊技术的新发展 - group of 2 »

史建卫, 何鹏, 钱乙余, 袁和平 - 电子工业专用设备, 2005 - 万方数据资源系统

... 1998, 35(1-2):61-64. [5] Farhad Sarvar*, Paul P. Conway. A modelling tool for the thermal optimisation of the **reflow** soldering of printed circuit assemblies ...[Related Articles](#) [Web Search](#)Wafer Level Lateral Bonding Scheme with LEGO-Like Structure - group of 2 »

E Lee, W Kim, I Song, C Moon, HC Kim, MK Kang, SD ... - Sensors and Materials, 2005 - minilab.snu.ac.kr

... The assembled pairs were put in the **reflow** oven to be heated under N₂ gas atmosphere. ...

9 F. Sarvar, DA Hutt and DC Whalley: IEEE Polytronic Conference (2002) 22 ...

[Related Articles](#) [Web Search](#) [SL Direct](#)Application of adhesives in MEMS and MOEMS assembly: a review - group of 2 »

F Sarvar, DA Hutt, DC Whalley - Polymers and Adhesives in Microelectronics and Photonics, ... , 2002 - ieeexplore.ieee.org

... Phone +44-1509-227661, Fax +44-1509-227645 Email: F.Sarvar@Lboro.ac.uk, DA ... Subsequent thermal treatment caused the PMMA to **reflow** forming the final lens shape. ...[Cited by 4](#) [Related Articles](#) [Web Search](#)A Wafer Level Packaging Approach for MEMS and Related Microsystems using Selective Laser ...

TOC View - Electronic Components and Technology, 2005. ECTC'05. ... - ieeexplore.ieee.org

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The Reflow Soldering Oven with LCD Display

The system would **interpolate** the temperatures for the in-between time ... There are several patents associated with the design of a **solder reflow oven**, ...
instruct1.cit.cornell.edu/courses/ee476/FinalProjects/s2006/ki38/Webpage/index.html - 61k - [Cached](#) - [Similar pages](#)

[PDF] DEVELOPMENT OF CONVECTIVE SOLDER REFLOW AND PROJECTION MOIRÉ ...

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and **interpolation** is required to obtain an accurate value. After the fringe order is ... The results showed that after **reflow**, the formed **solder** ...
etd.gatech.edu/theses/available/etd-04092003-222517/unrestricted/powell_reinhard_e_200605_phd.pdf - [Similar pages](#).

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evaluate the general **solder reflow** geometry shape,, and standoff height of the molten **solder**, ... restoring force **interpolation**. The hybrid solution ...
csmi9.pme.nthu.edu.tw:8080/csmi/pdf/history/machinical.pdf - [Similar pages](#)

Analysis of Interfacial Cracking in Flip Chip Packages With ...

This represents the temperature at which **solder reflow** and underfill cure are completed during manufacturing. Subjecting the package to a uniform brings the ...
link.aip.org/link/?JEPAE4/126/135/1 - [Similar pages](#)

Sci.Electronics.Repair FAQ: Notes on the Troubleshooting and ...

The **interpolation** used for oversampling and the **interpolation** and/or muting ... (Sure sounds like a fun project to me - **solder reflow** in your toaster oven! ...
www.repairfaq.org/REPAIR/F_cdqaqb.html - 39k - [Cached](#) - [Similar pages](#)

Publications :CMMS :King's College London

SH Mannan: **Solder Paste Reflow Modeling**. **Soldering and Surface Mount** ... H.-Y. Xu, JS Dai, and HY Tam: **Angular Interpolation for Planar Implicit Curves**. ...
www.kcl.ac.uk/schools/pse/diveng/research/cmms/pubs.html - 51k - [Cached](#) - [Similar pages](#).

[PDF] GS9078A HD-LINX® II Multi-Rate Cable Driver

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standard eutectic and Pb-free **solder reflow** profiles. ... **interpolate** the two return loss measurements. In this way, the values of return loss ...
www.gennum.com/video/pdf/34165DOC.pdf - [Similar pages](#)

Solid State Technology - Maximize your time on the exhibit floor ...

The Model 1200 tabletop vacuum **solder reflow** station is designed for process development and low-volume production of flux-free and void-free soldered ...
sst.pennnet.com/Articles/Article_Display.cfm?Section=Archives&Subsection=Display&ARTICLE_ID=180637 - 72k - [Cached](#) - [Similar pages](#)

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F Sarvar, PP Conway - Components, Packaging, and Manufacturing Technology, Part C, ..., 1998 - ieeexplore.ieee.org

... F. Sarvar and P. Conway, "A process modeling system for reflow soldering of surface ... Recent advances in thermal/flow simulation: Integrating thermal ...

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Effective transient process modelling of the reflow soldering of printed circuit assemblies - group of 2 »

F Sarvar, PP Conway - Thermal Phenomena in Electronic Systems, 1996, I-THERM V, ... - ieeexplore.ieee.org

... appropriate, the results of the first simulation to reduce ... the energy input to reflow the solder on PCAs. ... if needs be, to more detailed subsequent modeling. ...

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Board Level Solder Joint Reliability Modeling of TFBGA Package

TY Tee, HS Ng, S Pan - ICEP Conference Proc., Japan, 2002 - optimalcorp.com

... 4. R. Darveaux, "Effect of Simulation Methodology on Solder Joint Crack Growth ... al., "Board Level Solder Joint Reliability Modeling of LFBGA Package ...

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Yield Prediction for Flip-Chip Solder Assemblies Based on Solder Shape Modeling

SC Tower, B Su, YC Lee - IEEE TRANSACTIONS ON ELECTRONICS PACKAGING MANUFACTURING, 1999 - ieeexplore.ieee.org

... X. Zhang, and KA Brakke, "Computer simulation of solder ... [9] SK Patra and YC Lee, "Modeling of self ... chip soldering—Part II: Multichip solder joints," in ...

[Cited by 2](#) - Related Articles - Web Search - BL Direct

SOLDER REFLOW PREDICTION OF HYBRID PAD PACKAGING SYSTEM

CML Kuo-Ning Chiang - ieeexplore.ieee.org

... The Surface Evolver could Simulate the surface ... the Surface Evolver encounters modeling inconvenience and it ... Moreover, two SBM simulation models (analytical and ...

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Thermal Response of Electronic Assemblies during Forced Convection-Infrared Reflow

Soldering in an ... - group of 2 »

YS SON, JY SHIN - JSME International Journal Series B, 2005 - J-STAGE

... a collocated grid requires momentum interpolation to deter ... and Williams, DJ, The Process Modeling of the ... Thermal Effects during Infrared Solder Reflow—Part II ...

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Development of Convective Solder Reflow and Projection Moire System and FEA Model for PWBA Warpage ... - group of 2 »

RE Powell - 2006 - etd.library.gatech.edu

... Schematic of warpage measurement system to simulate convective reflow ... Simulation of Lee optimized reflow profile using the ... Effective modeling of a PBGA package ...

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